US 20060079156A1

(19) **United States**

(12) **Patent Application Publication**

(10) **Pub. No.: US 2006/0079156 A1**

(43) **Pub. Date: Apr. 13, 2006**

Polyak et al.

(54) **METHOD FOR PROCESSING A SUBSTRATE USING MULTIPLE FLUID DISTRIBUTIONS ON A POLISHING SURFACE**

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(21) Appl. No.: **11/262,620**

(22) Filed: **Oct. 31, 2005**

Related U.S. Application Data

(60) Continuation of application No. 11/176,985, filed on Jul. 8, 2005, which is a division of application No. 10/428,914, filed on May 2, 2003, now Pat. No. 6,939,210.

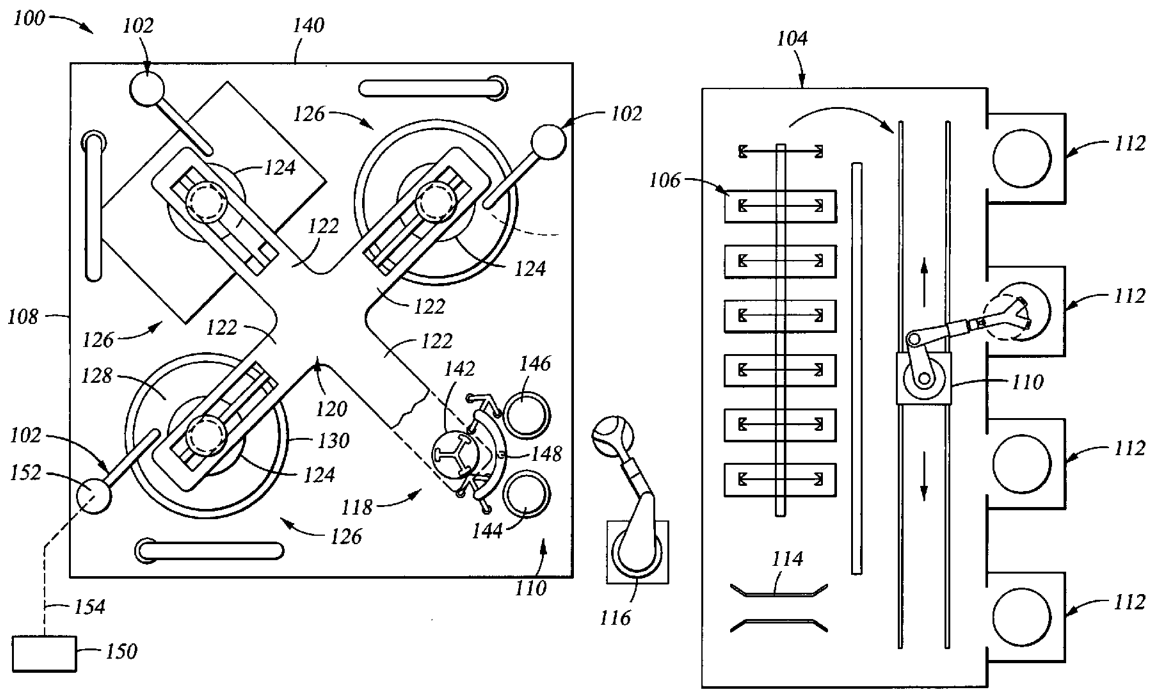
Publication Classification

(51) **Int. Cl.**
B24B 1/00 (2006.01)

(52) **U.S. Cl.** **451/41**

(57) **ABSTRACT**

A polishing fluid delivery apparatus has been provided that in one embodiment includes a support member, a dispense arm, a polishing fluid delivery tube and a variable restricting device. The dispense arm extends from an upper portion of the support member and has an outlet of the delivery tube coupled thereto. The restricting device interfaces with the delivery tube and is adapted to provide a variable restriction to flow passing through the delivery tube. In another embodiment, the restricting device is a pinch valve and the tube in continuous from the outlet to beyond a portion that interfaces with the pinch valve. In yet another embodiment, the position of the dispense arm is controllable.



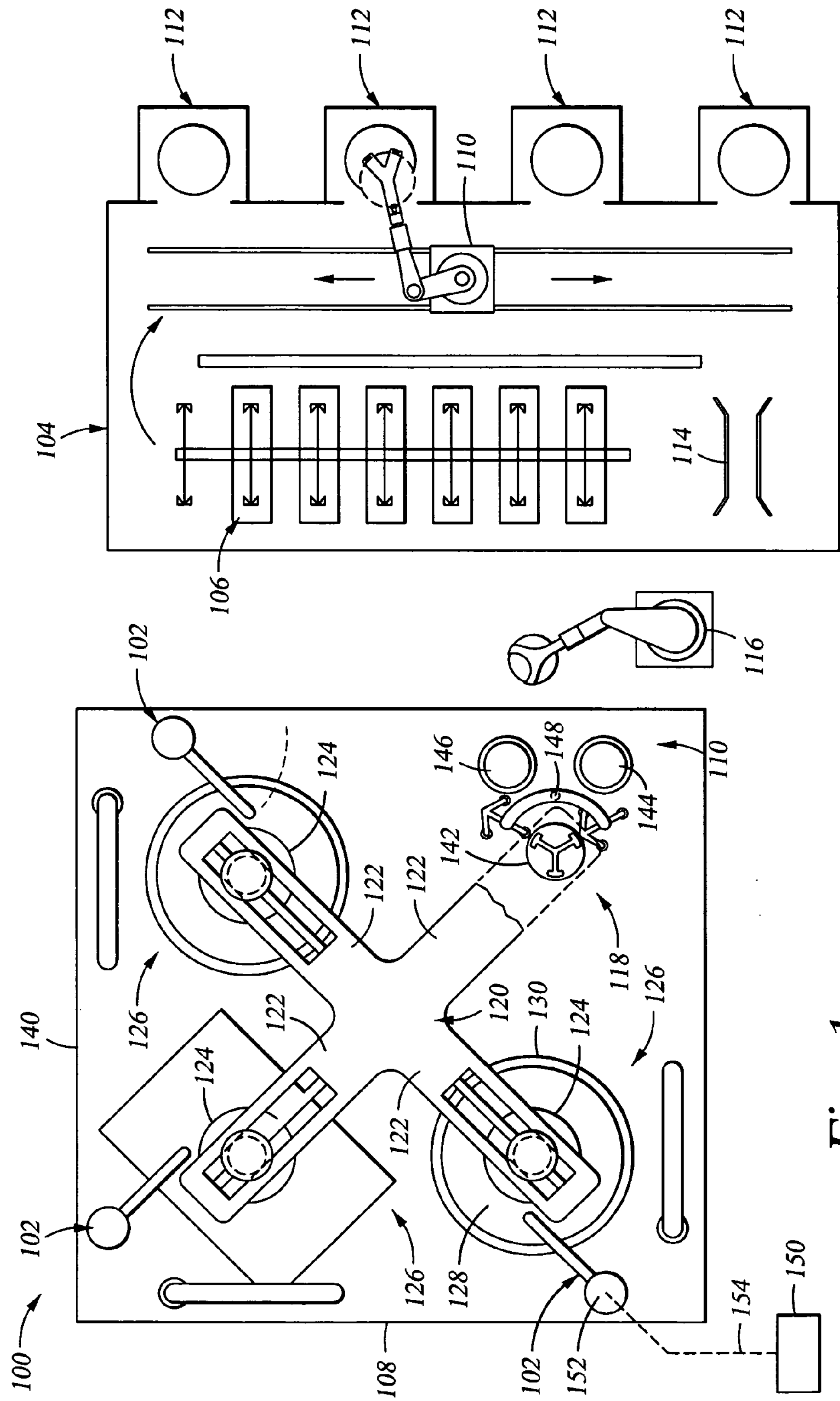

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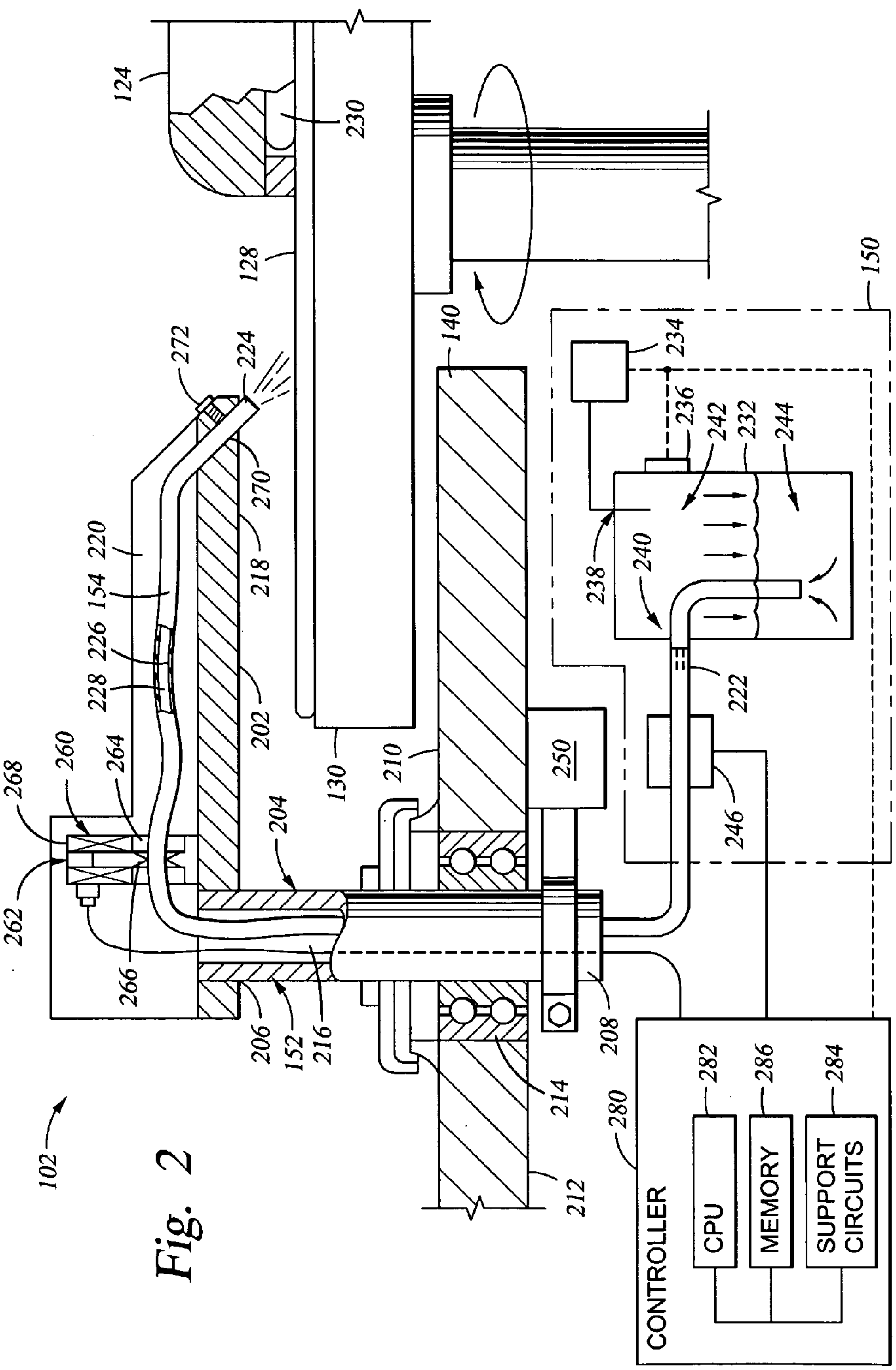
Fig. 1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228
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232
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238
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242
244
246
250
260
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264
266
268
270
272
280
282
284
286
CONTROLLER
CPU
MEMORY
SUPPORT CIRCUITS

Fig. 2

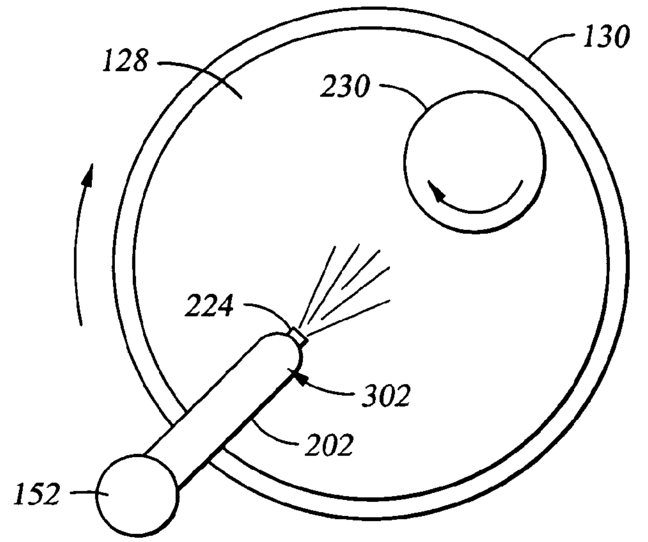


Fig. 3A

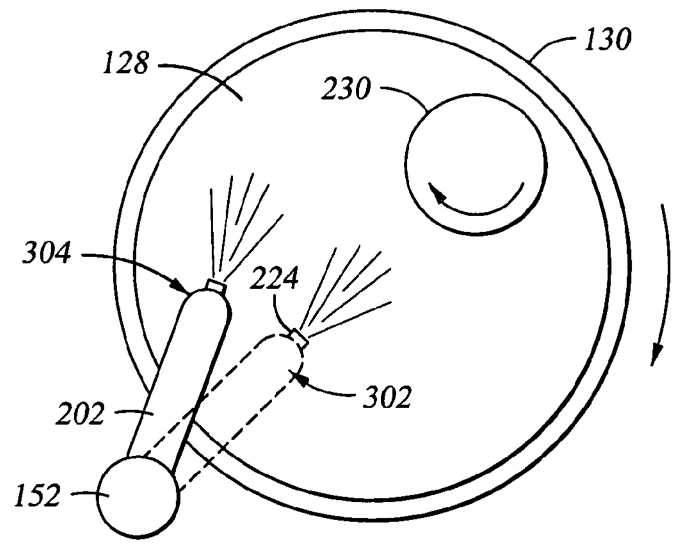


Fig. 3B

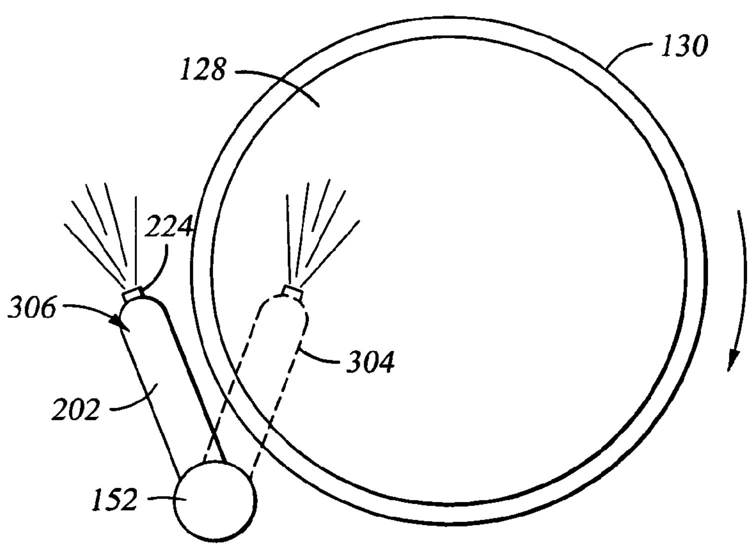
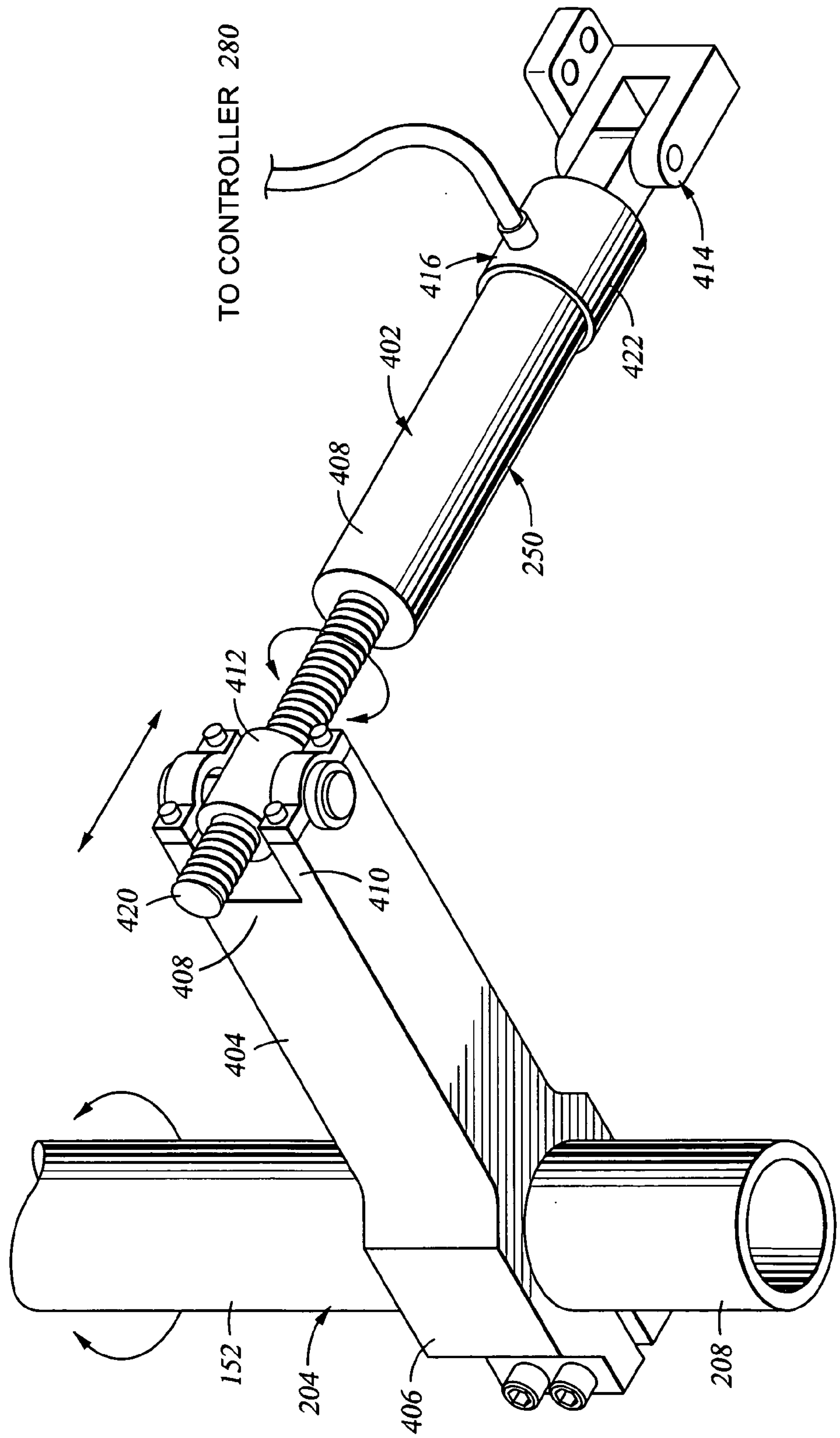


Fig. 3C


TO CONTROLLER 280
416
414
422
402
408
250
412
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410
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404
152
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208

Fig. 4

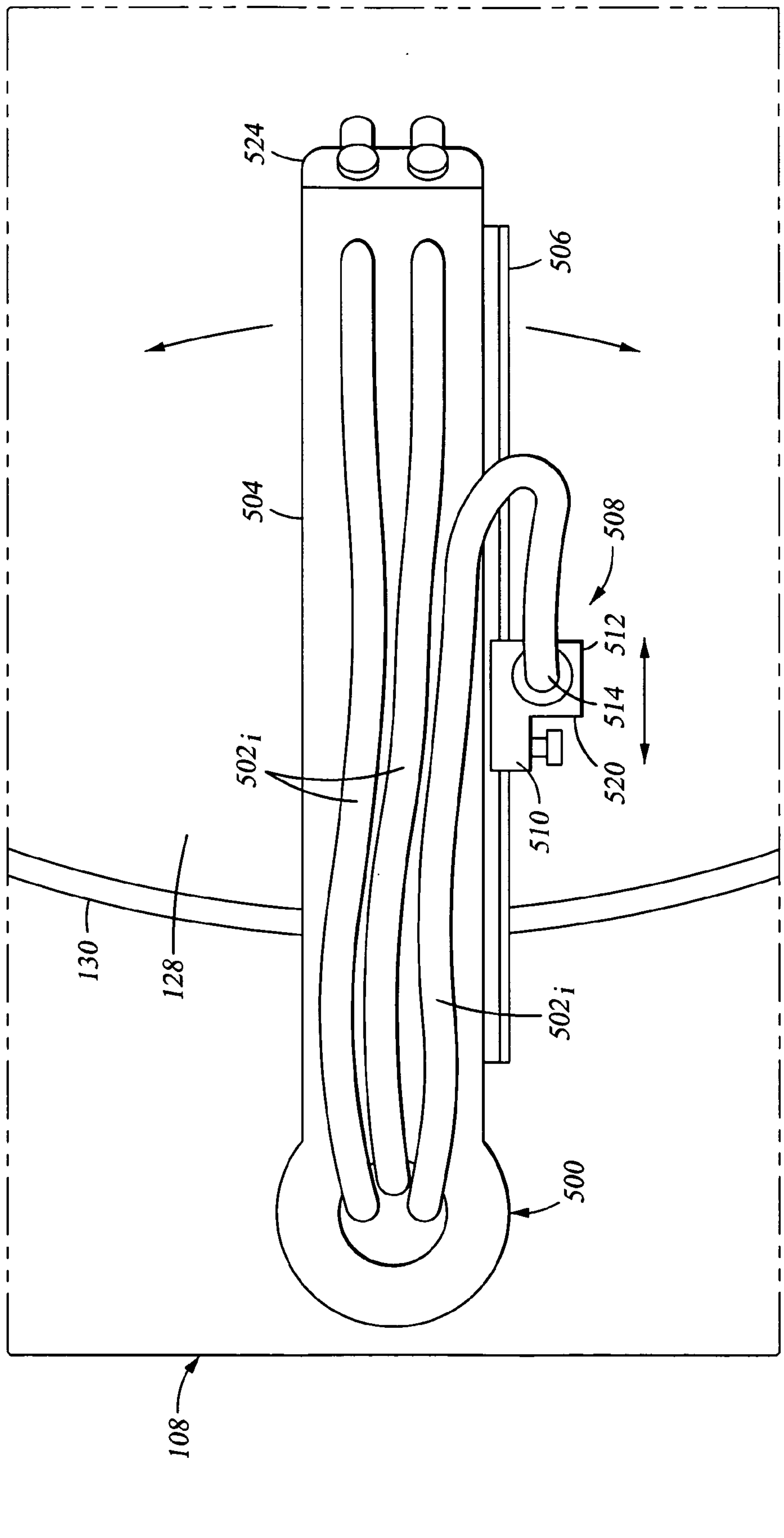

Fig. 5

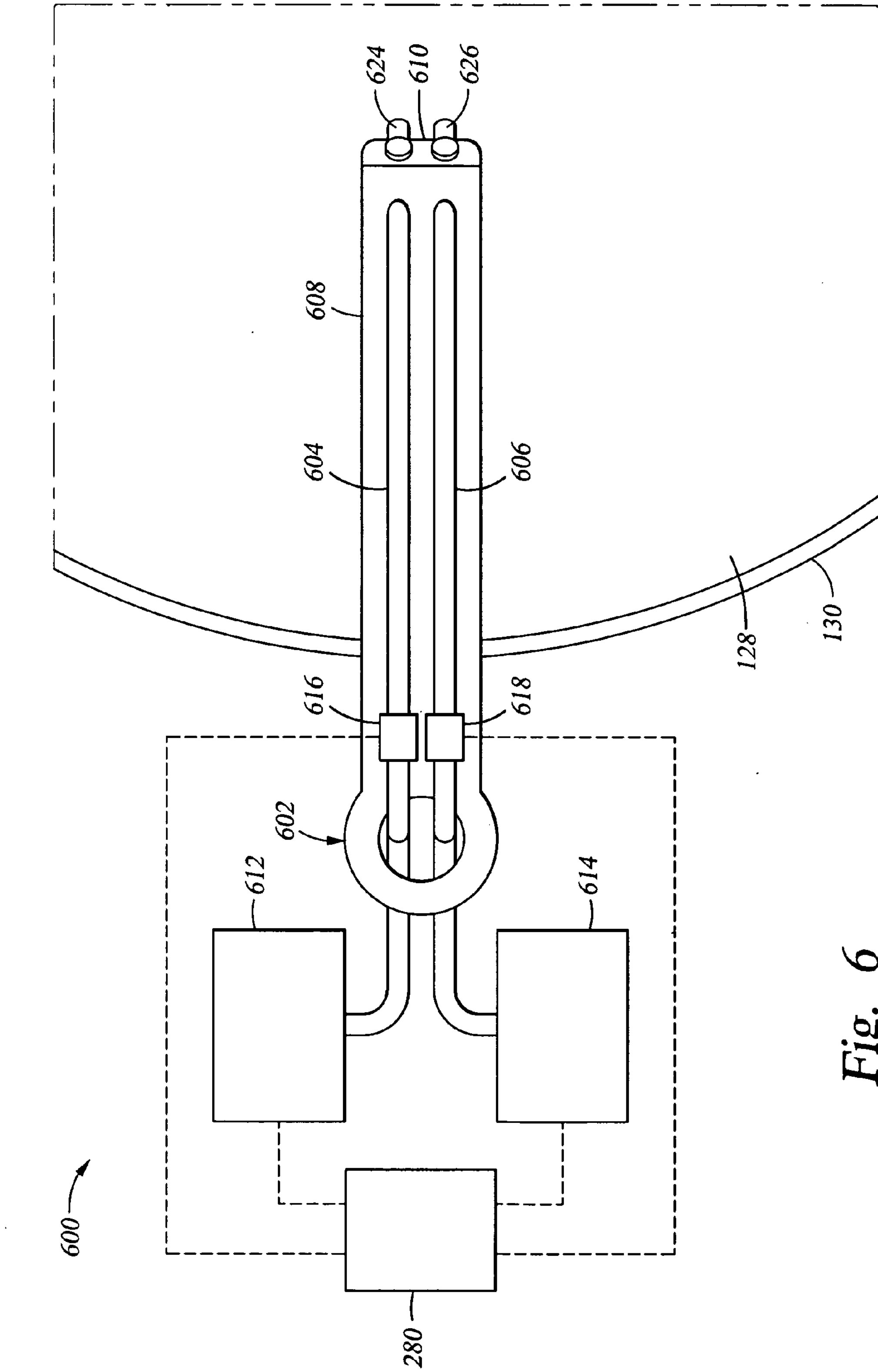

Fig. 6

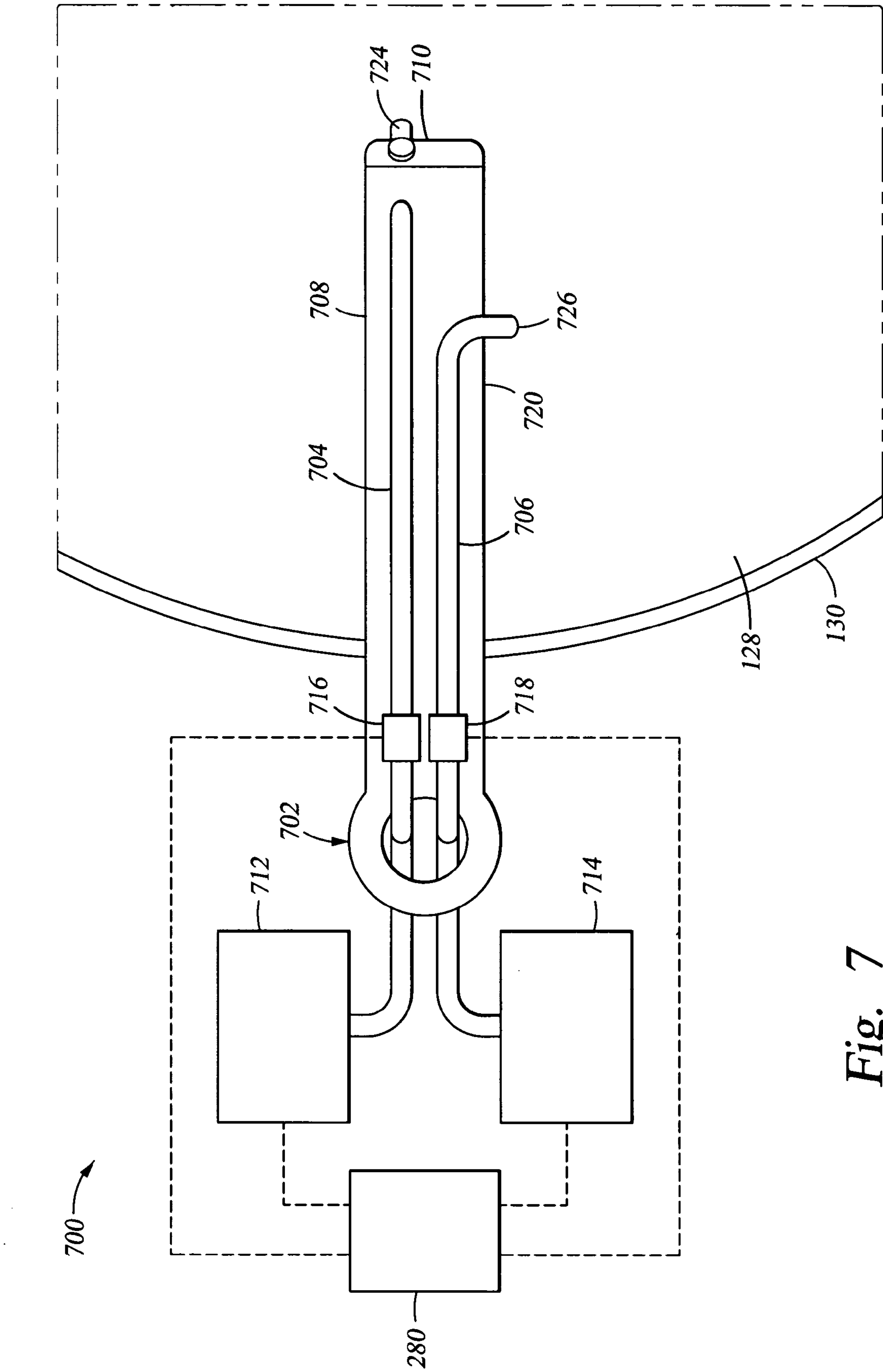

Fig. 7

METHOD FOR PROCESSING A SUBSTRATE USING MULTIPLE FLUID DISTRIBUTIONS ON A POLISHING SURFACE

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application is a continuation of U.S. patent application Ser. No. 11/176,985, filed Jul. 8, 2005, which is a divisional application of co-pending U.S. Pat. No. 6,939,210, issued Sep. 6, 2005, all of which are hereby incorporated by reference in their entireties.

BACKGROUND OF THE INVENTION

[0002] 1. Field of the Invention

[0003] Embodiments of the present invention generally relate to a method for processing a substrate in a chemical mechanical polishing system.

[0004] 2. Description of the Related Art

[0005] Chemical mechanical polishing is one process commonly used in the manufacture of high-density integrated circuits. Chemical mechanical polishing is utilized to planarize a layer of material deposited on a semiconductor wafer by moving the substrate in contact with a polishing surface while in the presence of a polishing fluid. Material is removed from the surface of the substrate that is in contact with the polishing surface through a combination of chemical and mechanical activity. One type of polishing fluid commonly used in chemical mechanical polishing applications is a slurry containing chemical agents and abrasive particles. The abrasive particles in the slurry enhance the mechanical removal of material from the substrate while exposing the underlying surface to the chemical agents in the polishing fluid.

[0006] Polishing fluid is typically provided to the polishing surface through a dispense arm that is positioned over the polishing surface during processing. The dispense point (i.e., the point at which the polishing fluid flows from a delivery tube to the polishing surface), and the amount and concentration of polishing fluid provided to the polishing surface are attributes that impact the quality of substrate processing. To ensure acceptable polishing results, conventional polishing fluid delivery systems rely on detent mechanisms to ensure repeatable positioning of the polishing fluid dispense arm at a pre-defined dispense location along with various flow control devices utilized to monitor and control the amount and concentration of polishing fluid delivered to the polishing surface.

[0007] One problem associated with this conventional arrangement is that the polishing fluid dispense arm is limited to the pre-defined position wherein the detent mechanism engages the arm. Thus, control of the dispense point on the polishing surface is limited to physically changing the delivery tube's position along the arm. Thus, in order to change the dispense point to achieve a desired processing result, polishing must be interrupted to allow for service personnel to mechanically adjust the position of the nozzles along the length of the slurry dispense arm, thereby increasing the risk of equipment damage and disadvantageously decreasing substrate throughput.

[0008] Another issue affecting many conventional polishing fluid delivery systems is the tendency of abrasive particles within the slurry to attach and agglomerate at tube fittings and around flow control components. For example, the interfaces between the slurry delivery tube and tees, valves, restrictors or other devices include small seams or gaps along the flow path where abrasive particles from within the slurry tend to adhere and conglomerate. As the number of abrasive particles accumulating at these locations grows, chains or groups of the conglomerated particles break free and travel downstream through the delivery tube to the polishing surface where they come in contact with the surface of the substrate being polished. These conglomerated particles often cause scratching of the substrate surface and defect generation. Therefore, it would be desirable to minimize and/or eliminate any seams along the slurry flow path to minimize the introduction of conglomerated particles to the polishing surface.

[0009] Therefore, there is a need for an improved slurry delivery system.

SUMMARY OF THE INVENTION

[0010] A polishing fluid delivery apparatus has been provided that in one embodiment includes a support member, a dispense arm, at least one polishing fluid delivery tube and a variable restricting device. The dispense arm extends from an upper portion of the support member and has an outlet of the delivery tube coupled thereto. The restricting device interfaces with the delivery tube and is adapted to provide a variable restriction to flow passing through the delivery tube. In another embodiment, the restricting device is a pinch valve and the tube is continuous from the outlet to beyond a portion that interfaces with the pinch valve. In yet another embodiment, the position of the dispense arm is controllable.

BRIEF DESCRIPTION OF THE DRAWINGS

[0011] A more particular description of the invention, briefly summarized above, may be had by reference to the embodiments thereof that are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only typical embodiments of this invention and are therefore not to be considered limiting of its scope, for the invention may admit to other equally effective embodiments.

[0012] **FIG. 1** is a top view of an illustrative chemical mechanical polishing system having one embodiment of a polishing fluid delivery system;

[0013] **FIG. 2** is a sectional view of a polishing fluid dispense arm of the polishing fluid delivery system of **FIG. 1**;

[0014] FIGS. **3**A-C are simplified top views of the polishing fluid dispense arm in various positions;

[0015] **FIG. 4** is a bottom perspective view of one embodiment of a polishing fluid dispense arm;

[0016] **FIG. 5** is a top view of another embodiment of a polishing fluid dispense arm; and

[0017] **FIGS. 6-7** are simplified top views of other embodiments of a polish fluid delivery system.

[0018] To facilitate understanding, identical reference numerals have been used, wherever possible, to designate identical elements that are common to the figures.

DETAILED DESCRIPTION

[0019] **FIG. 1** is a top view of an illustrative chemical mechanical polishing system **100** having one embodiment of a polishing fluid delivery system **102** of the present invention. The chemical mechanical polishing system **100** generally includes a factory interface **104**, a cleaner **106** and a polisher **108**. One polishing system **100** that may be adapted to benefit from the invention is a REFLEXION® chemical mechanical polishing system, available from Applied Materials, Inc., located in Santa Clara, Calif. Another polishing system **100** that may be adapted to benefit from the invention is described in U.S. Pat. No. 6,244,356, issued Jul. 2, 2002 to Birang, et al., which is incorporated by reference in its entirety.

[0020] In one embodiment, the factory interface **104** includes a first or interface robot **110** adapted to transfer substrates from one or more substrate storage cassettes **112** to a first transfer station **114**. A second robot **116** is positioned between the factory interface **104** and the polisher **108** and is configured to transfer substrates between the first transfer station **114** of the factory interface **104** and a second transfer station **118** disposed on the polisher **108**. The cleaner **106** is typically disposed in or adjacent to the factory interface **104** and is adapted to clean and dry substrates returning from the polisher **108** before being returned to the substrate storage cassettes by the interface robot **110**.

[0021] The polisher **108** includes at least one polishing station **126** and a transfer device **120** disposed on a base **140**. In the embodiment depicted in **FIG. 1**, the polisher **108** includes three polishing stations **126**, each having a platen **130** that supports a polishing material **128** on which the substrate is processed.

[0022] The transfer device **120** supports at least one polishing head **124** that retains the substrate during processing. In the embodiment depicted in **FIG. 1**, the transfer device **120** is a carousel supporting one polishing head **124** on each of four arms **122**. One arm **122** is cutaway to show the second transfer station **118**. The transfer device **120** facilitates moving substrates retained in each polishing head **124** between the second transfer station **118** and the polishing stations **126** where substrates are processed. The polishing head **124** is configured to retain a substrate while polishing. The polishing head **124** is coupled to a transport mechanism that is configured to move the substrate retained in the polishing head **124** between the transfer station **118** and the polishing stations **126**. One polishing head **124** that may be adapted to benefit from the invention is a TITAN HEAD™ substrate carrier, available from Applied Materials, Inc.

[0023] The second transfer station **118** includes a load cup **142**, an input buffer **144**, an output buffer **142** and a transfer station robot **148**. The input buffer **144** accepts a substrate being transferred to the polisher **108** from the second robot **116**. The transfer station robot **148** transfers the substrate from the input buffer **144** to the load cup **142**. The load cup **142** transfers the substrate vertically to the polishing head **124**, which retains the substrate during processing. Polished substrates are transferred from the polishing head **124** to the load cup **142**, and then moved by the transfer station robot **148** to the output buffer **142**. From the output buffer **142**, polished substrates are transferred to the first transfer station **114** by the second robot **116** and then transferred through the cleaner **106**. One second transfer station **118** that may be adapted to benefit from the invention is described in U.S. Pat. No. 6,156,124, issued Dec. 5, 2000, to Tobin, which is incorporated by reference in its entirety.

[0024] In one embodiment, the polishing station **126** includes a platen **130** that supports a polishing material **128**. During processing, the substrate is held against the polishing material **128** by the polishing head **124**. The platen **130** rotates to provide at least a portion of the polishing motion imparted between the substrate and the polishing material **128**. Alternatively, the polishing motion may be imparted by moving at least one of the polishing head **124** or polishing material **128** in a linear, orbital, random, rotary or other motion.

[0025] The polishing material **128** may be comprised of a foamed polymer, such as polyurethane, or may be a fixed abrasive material. Fixed abrasive material generally includes a plurality of abrasive elements disposed on a flexible backing. In one embodiment, the abrasive elements are comprised of geometric shapes formed from abrasive particles suspended in a polymer binder. The polishing material **128** may be in either pad or web form.

[0026] The polishing fluid delivery system **102** includes at least one polishing fluid supply **150** coupled to at least one polishing fluid dispense arm assembly **152**. Generally, each polishing station **126** is equipped with a respective dispense arm assembly **152** positioned proximate to the respective platen **130**. In the embodiment depicted in **FIG. 1**, the three polishing stations **126** each have one dispense arm assembly **152** associated therewith. Each polishing fluid dispense arm assembly **152** may be coupled to a dedicated polishing fluid supply **150**, or may be configured to receive polishing fluid from a single or multiple shared polishing fluid supplies. Each dispense arm assembly **152** includes at least one fluid delivery tube **154** coupled to the polishing fluid supply **150**.

[0027] **FIG. 2** depicts a sectional view of one embodiment of the polishing fluid dispense arm assembly **152**. The polishing fluid dispense arm assembly **152** includes a dispense arm **202** affixed to and extending laterally from the upper portion **206** of a support member **204** above a top surface **210** of the base **140**. The lower portion **208** of the support member **204** is rotatably mounted in and extends through a bottom **212** of the base **140**. A bearing assembly **214** is disposed between the support member **204** and the base **140** to allow the dispense arm **202** extending from the upper portion **206** of the support member **204** to be rotated between a standby or purge position clear of the platen **130** and a dispense position over the polishing material **128** (as shown in **FIG. 1**).

[0028] For simplicity in the embodiment depicted in **FIG. 2**, a single delivery tube **154** is shown routed along the dispense arm **202** for supplying polishing fluid to the polishing material **128** disposed on the platen **130**. However, any number of delivery tubes **154** may be utilized to supply polishing fluid from a common dispense arm **202** to a single platen **130**. The delivery tube is comprised of a resilient and flexible material, such as silicone. The interior of the tube must be substantially free of interior anomalies.

[0029] In one embodiment, the delivery tube **154** is routed from an inlet end **222** coupled to the polishing supply **150** through a passage **216** formed in the support member **204** and outward along a channel **220** disposed in the dispense arm **202**. An outlet end **224** of the delivery tube **154** is positioned at a distal end **218** of the dispense arm **202**. The distal end **218** includes a tube receiving passage **270** through which the outlet end **224** of the delivery tube **154** is disposed. The delivery tube **154** is secured in the passage **270** by a clamp **272**, which in one embodiment is a set screw. Alternatively, the delivery tube **154** may be positioned at other locations along the length of the dispense arm **202**. In embodiments utilizing multiple delivery tubes **154**, any one of the tubes may be fixed to or positionable along the dispense arm **202**, and have their outlet ends **224** grouped in a common location or spaced apart to dispense polishing fluid at predefined locations across the diameter of the polishing material **128**.

[0030] In one embodiment, the delivery tube **154** is a single, continuous member running from its inlet to outlet ends **222**, **224**. The delivery tube **154** has no crevasses, seams or other anomalies present along its inner surface **226** that would otherwise provide attachment points for abrasive or other particles that may be entrained or form in the polishing fluid, thereby advantageously decreasing the probability of particle agglomeration within the tube and there release to the polishing material **128** where they may contact a substrate **130** being processed. The substantial elimination of release of agglomerated particles results in increased product yield by reducing scratching and substrate defects. Alternatively, the delivery tube **154** may be segmented, but with increased potential for diminished yield.

[0031] In one embodiment, the polishing fluid supply **150** includes a pressure vessel **232** and a pressure control system **234**. The pressure vessel **232** contains a polishing fluid **244**, and may be optionally coupled to a bulk supply system (not shown) for periodic replenishment of polishing fluid. The pressure vessel **232** has an inlet port **238** and outlet port **240**. The inlet port **238** is coupled to the pressure control system **234** while the outlet port **240** is coupled to inlet end **222** of the delivery tube **154**.

[0032] The pressure control system **234** generally controls the pressure within and/or delivers gas to the pressure vessel **232**. Gas **242** within the pressure vessel **232** imparts a pressure on the polishing fluid **244** residing in the pressure vessel **232**, thereby driving the polishing fluid **244** through the outlet port **240** and the delivery tube **154**, and ultimately flowing out the outlet end **224** to the polishing material **128**. The pressure control system **234** may include regulators, pumps and the like to control the pressure applied to the polishing fluid **244** disposed in the pressure vessel **232**. A pressure sensor **236** is coupled to the pressure vessel **232** to provide a metric indicative of the pressure within the pressure vessel **232**.

[0033] A flow sensor **246** is interfaced with the delivery tube **154** to provide a metric indicative of the flow of polishing fluid passing therethrough. In embodiments where the delivery tube **154** is configured to flow fluids not prone to particle formation, for example de-ionized water and chemical reagents, flow sensors that engage the fluid, such as paddle wheels and the like may be utilized. In embodiments where the delivery tube **154** is configured to flow fluids containing particles and/or prone to particle formation, such as abrasive containing slurries, non-intrusive flow sensors, such as sonic flow transducers and the like may be utilized to maintain a continuous non-interrupted inner wall integrity of the delivery tube **154** between the polishing fluid supply **150** and the outlet end **224** of the delivery tube **154**.

[0034] To enhance control over the polishing fluid flowing through the polishing fluid delivery tube **154**, a variable restricting device **260** is utilized to interface with the delivery tube **154**. In the embodiment depicted in **FIG. 2**, the restricting device **260** is configured to apply a bias to the exterior of the delivery tube **154**, resulting in a reduction of the interior sectional area **228** of the delivery tube **154** resulting in a flow restriction to the polishing fluid flowing therethrough. As the restricting device **260** is non-intrusive, i.e., does not create a seam in the flow path or otherwise contact the polishing fluid flowing through the tube, flow attributes, such as backpressure, which may be utilized to control the flow through the tube, may be controlled without creating surface conditions such as a seam that encourages the attachment and build-up of particles.

[0035] Moreover, as the restricting device **260** is configured to provide a variable restriction, the flow of polishing fluid through the delivery tube **154** to the polishing material **128** may be controlled through a full range of flow conditions as desired. For example, the restricting device **260** may completely close the interior sectional area **228** of the delivery tube **154** resulting in zero polishing fluid flow. The restricting device **260** may also partially close the delivery tube **154** to a predefined percentage of the open sectional area **228**, or the restricting device **260** may leave the sectional area **228** of the delivery tube **154** substantially open in a full flow condition. One benefit of completely opening the delivery tube **154** to a full flow condition is that the increased flow rate through the delivery tube **154** sweeps any particles that may have attached to the tube walls or other components disposed in the polishing fluid flow path out of the delivery tube **154** during a purge cycle between polishing, thereby further reducing incidence of agglomerated particles reaching the substrate during processing.

[0036] In one embodiment, the restricting device **260** is a pinch valve **262** having a slot **264** for receiving the delivery tube **154**. The pinch valve **262** includes an actuation bar **266** coupled to an actuator **268** that selectively biases the bar **266** against the exterior of the delivery tube **154** to control the amount that the inner sectional area **228** of the delivery tube **154** is open to flow.

[0037] The pinch valve **262** may be positioned anywhere along the length of the delivery tube **154**. In the embodiment depicted in **FIG. 2**, the pinch valve **262** is coupled to at least one of the dispense arm **202** or support member **204** of the dispense arm assembly **152**.

[0038] The pinch valve's actuator **268** may be a solenoid, linear actuator, cam, electric motor and ball screw, pneumatic cylinder, hydraulic cylinder or other device capable of biasing the delivery tube **154** to control flow therethrough. In one embodiment, the actuator **268** is configured to apply a controlled actuation pressure, thereby allowing the inner sectional area **228** of the delivery tube **154** to be controlled between any incremental opening amount between completely closed to completely open. In another embodiment, the actuator **288** variably controls the stroke distance of the bar **266**, thereby allowing the inner sectional area **228** of the delivery tube **154** to be set at a predefined percentage of full open.

[0039] To facilitate control of the system **100** as described above, a controller **280** is coupled to the chemical mechanical polishing system **100**. The controller **280** includes a CPU **282**, support circuits **284** and memory **286**. The CPU **282** may be one of any form of computer processor that can be used in an industrial setting for controlling various chambers and subprocessors. The memory **286** is coupled to the CPU **282**. The memory **286**, or computer-readable medium, may be one or more of readily available memory such as random access memory (RAM), read only memory (ROM), floppy disk, hard disk, or any other form of digital storage, local or remote. The support circuits **284** are coupled to the CPU **282** for supporting the processor in a conventional manner. These circuits include cache, power supplies, clock circuits, input/output circuitry and subsystems, and the like. A process, for example a polishing process described below, is generally stored in the memory **286**, typically as a software routine. The software routine may also be stored and/or executed by a second CPU (not shown) that is remotely located from the hardware being controlled by the CPU.

[**0040**] Although the process of the present invention is discussed as being implemented as a software routine, some of the method steps that are disclosed therein may be performed in hardware as well as by the software controller. As such, the invention may be implemented in software as executed upon a computer system, in hardware as an application specific integrated circuit or other type of hardware implementation, or a combination of software and hardware.

[**0041**] In one embodiment, the pressure control system **234**, the pressure sensor **236**, flow sensor **246** and restricting device **260** are coupled to the controller **280** to allow closed loop control over the amount of polishing fluid flowing through the delivery tube **154**. The controller **280** compares the sensed flow value resolved from the metric provided by the flow sensor **246** with a target value. In response, the controller **280** instructs at least one of the pressure within the pressure vessel **232** (as controlled by the pressure control system **234**) and the restriction (i.e., backpressure) created by the restricting device **260** (as controlled by the open area of the delivery tube **154**) to be adjusted so that the sensed flow is maintained at substantially equal the target value.

[**0042**] **FIGS. 6-7** depict alternate embodiments of polishing fluid delivery systems that are adapted to control the distribution of polishing fluid on the surface of a polishing material **128**. In the embodiment depicted in **FIG. 6**, a polishing fluid delivery assembly **600** includes a dispense arm assembly **602** having a first delivery tube **604** and a second delivery tube **606** coupled to a dispense arm **608**. Outlet ends **624**, **626** of the tubes **604**, **606** are positioned at a distal end **610** of the dispense arm **608**.

[**0043**] The first delivery tube **604** is coupled to a first fluid source **612** through a variable restricting device **616**. The second delivery tube **606** is coupled to a second fluid source **614** through a second restricting device **618**. In one embodiment, the first fluid source **612** may be configured to provide one component of the polishing fluid while the second fluid source **614** may be configured to provide another component of the polishing fluid such that the components of the polishing fluid provided by the supplies **612**, **614** are mixed on the polishing material **128** after flowing from the outlets **624**, **626** of the tubes **604**, **606**.

[**0044**] A controller **280** interfaces with the supplies **612**, **614** and restricting devices **616**, **618** in the manner described above that the ratio between the fluid supplied through the first tube **604** and the second tube **606** may be maintained at a predetermined value, or changed as desired to yield a desired polishing result. In one example, the first fluid source **612** may provide a slurry while the second fluid source **614** provides deionized water. By controlling the fluid flows through each tube **604**, **606**, a controlled slurry flow from the first delivery tube **604** is diluted on the polishing materials **128** by a controlled water flow from the second delivery tube **606**, thereby allowing the concentration of polishing fluid disposed on the polishing material **128** to be varied as required, for example, to polish a specific material or in-situ while polishing a single substrate.

[**0045**] In the embodiment depicted in **FIG. 7**, a polishing fluid delivery assembly **700** includes a dispense arm assembly **702** having a first delivery tube **704** and a second delivery tube **706** coupled to a dispense arm **708**. The outlet end **724** of the first delivery tube **704** is positioned at a distal end **710** of the dispense arm **708**. The outlet end **726** of the second delivery tube **706** is positioned along a lateral side **720** of the dispense arm **708**.

[**0046**] The first delivery tube **704** is coupled to a first fluid source **712** through a variable restricting device **716**. The second delivery tube **706** is coupled to a second fluid source **714** through a second restricting device **718**. In one embodiment, the first and second fluid sources **712**, **174** may be configured to provide the same concentration of polishing fluid, and as such, may be combined as a single source.

[**0047**] A controller **280** interfaces with the supplies **712**, **714** and restricting devices **716**, **718** as described above so that the ratio between the fluid supplied through the first tube **704** and the second tube **706** may be maintained at a predetermined value, or changed as desired to yield a desired polishing result. In one example, the first fluid source **712** may provide a greater flow of polishing fluid through the first delivery tube **704** as compared to the flow through the second delivery tube **706**, thereby causing the center of the substrate to be polished at a rate different than the edge. By controlling the fluid flows through each tube **704**, **706**, the rate of polishing across the profile of the substrate may be controlled from substrate to substrate, or in-situ during the polishing of a single substrate.

[**0048**] In another embodiment, the first and second fluid sources **712**, **174** may be configured to provide the different components of polishing fluid or different types of polishing fluid. The controller **280** enables the ratio of fluid supplied through the first tube **704** and the second tube **706** may be controlled, thereby facilitating control over the rate of polishing across the profile of the substrate.

[**0049**] Returning to **FIG. 2**, the dispense arm assembly **152** additionally includes an actuator **250** coupled to the lower portion **208** of the support member **204** to control the angular orientation of the dispense arm **202**. The actuator **250** may be a gear motor, a harmonic drive, a linear actuator, a motorized lead screw, a hydraulic cylinder, a pneumatic cylinder or other device suitable for imparting rotation to the dispense arm **202** about the support member **204**. The actuator **250**, in response to instructions from the controller **280**, rotates the support member **204** and dispense arm **202**, thereby controlling the position of the outlet end **224** of the delivery tube **154** over the polishing material **128**, for example, between a first dispense position **302**, a second dispense position **304** and a purge position **306**, as shown in the simplified top view of the polishing fluid dispense arm assembly depicted in FIGS. 3A-C. In this manner, the distribution of polishing fluid across the width of the polishing material **128** may be controlled by adjusting the relative position of the outlet end **224** (i.e., dispense points) and the polishing material **128**. As the distribution of polishing fluid interfacing with the substrate on the polishing material **128** is changed, the rate of material removal (e.g., polishing) may be controlled as desired. For example, more polishing fluid may be provided to the areas of the polishing material **128** that predominantly contact the perimeter of the substrate, thereby polishing the perimeter of the substrate faster than the center.

[**0050**] **FIG. 4** depicts a bottom perspective view of one embodiment of polishing fluid dispense arm assembly **152** having a ball screw actuator **402** to control the rotational position of the dispense arm **202**. The ball screw actuator **402** is coupled to the lower portion **208** of the support member **204** by a control arm **404**. The control arm **404** has a first end **406** coupled to the lower portion **208** of the support member **204** that extends below the base **140** of the polisher **108** and a second end **408**. The second end **408** includes a bifurcated flange **410** configured to pivotally retain a drive nut **412** therebetween.

[**0051**] The ball screw actuator **402** has a mounting portion **416** that is coupled to the base **140** of the polisher **108** by a gimbal **414**. A motor **418** is disposed on the mounting portion **416** and is coupled to the controller **280**. A ball screw **420** or other thread form extends from the motor **418** and engages the drive nut **412**. As the motor **420** rotates the ball screw **420**, the drive nut **412** retained by the second end **408** of the control arm **404** is urged towards (or away from) the motor **418**, thereby causing the support member **204** and dispense arm **202** to rotate.

[**0052**] A position sensor **422** is interfaced with the dispense arm assembly **152** to provide a metric indicative of the position of the dispense arm **202**. The position sensor **422** may be any sensor suitable for providing positional information, such as linear displacement transducers, proximity switches and limit switches, among others. In one embodiment, the position sensor **422** is a rotary encoder coupled to at least one of the motor **418** or ball screw **420** for providing a metric indicative of the ball screw's rotation, which corresponds to a predefined advance of the drive nut **412** along the ball screw **420**, from which the position of the dispense arm **202** and tube outlet end **224** may be resolved. The position sensor **422** may work in concert with limit switches (not shown) to provide reference coordinate information regarding of the range of motion of the dispense arm **202** at system start-up.

[**0053**] **FIG. 5** depicts another embodiment of a polishing fluid dispense arm assembly **500**. The dispense arm assembly **500** is substantially similar to the dispense arm assembly **152** described above, except wherein at least a first fluid delivery tube $\mathbf{502}_1$ of a plurality of fluid delivery tubes $\mathbf{502}_i$ is positionable longitudinally along a dispense arm **504** rotationally supported over a top surface of a polisher **108**. In the embodiment depicted in **FIG. 5**, at least one of the fluid delivery tubes $\mathbf{502}_i$ is coupled to a distal end **524** of the dispense arm **504**.

[**0054**] In one embodiment, the dispense arm **504** includes a track **506** along which a tube clamp **508** may be selectively positioned. The tube clamp **508** includes a first clamp **510** and a second clamp **512**. The first clamp **510** is disposed through the tube clamp **508** and may be biased against the track **506** to secure the position of the tube clamp **508** along the lateral length of the dispense arm **504**. The tube clamp **508** additionally includes a tube receiving passage **514** that accepts an outlet end **520** of the first fluid delivery tube $\mathbf{502}_1$. The second clamp **512** is configured to secure the first fluid delivery tube **502**, in the tube receiving passage **514**. Optionally, additional tube clamps **508** may be coupled to the track **506** to retain other tubes $\mathbf{502}_i$ at predefined intervals along the dispense arm **504**. One dispense arm **504** that may be adapted to benefit from the invention is described in U.S. patent application Ser. No. 10/131,638, filed Apr. 22, 2002, by Vereen et al., which is incorporated by reference in its entirety.

[**0055**] Thus, a polishing fluid delivery system has been provided that advantageously reduces the incidence of particle collection and release to a polishing surface, thus decreasing the occurrence of substrate scratching and defect generation. In another aspect of the invention, a polishing fluid delivery system has been provided that controls the distribution of polishing fluid across the width of a polishing material, advantageously allowing the polishing rates across the profile of a substrate to be controlled.

[**0056**] While the foregoing is directed to the preferred embodiment of the present invention, other and further embodiments of the invention may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow.

What is claimed is:

1. A method for polishing substrate, comprising:

creating a first distribution of polishing fluid on a polishing surface;

polishing a substrate on the polishing surface in the presence of the first fluid distribution;

repositioning a polishing fluid dispense arm to create a second distribution of polishing fluid on the polishing surface; and

polishing the substrate on the polishing surface in the presence of the second fluid distribution.

2. The method of claim 1, wherein the step of repositioning the polishing fluid dispense arm further comprises:

radially moving a fluid outlet disposed on the arm relative to the polishing surface.

3. The method of claim 1, wherein the step of repositioning the polishing fluid dispense arm further comprises:

moving a fluid outlet disposed on the arm parallel to the polishing surface.

4. The method of claim 1, wherein the step of repositioning the polishing fluid dispense arm further comprises:

rotating the arm.

5. The method of claim 1, wherein the step of moving the polishing fluid dispense arm further comprises:

changing a volumetric distribution of fluid on the polishing surface.

6. The method of claim 1 further comprising:

moving the polishing fluid dispense arm clear of the polishing surface; and

flowing a fluid through the polishing fluid dispense arm at an increased flow rate relative to a flow rate utilized to create at least one of the first or second fluid distribution.

7. The method of claim 6, wherein the flow rate in the position clear of the polishing surface is greater than flow rates utilized to create the first and second polishing fluid distributions.

8. The method of claim 1 further comprising:

detecting a metric indicative of material removed while polishing the substrate in the presence of the first fluid distribution; and

moving the dispense arm in response to the detected metric.

10. A method for processing a substrate, comprising:

moving a dispense arm into a first dispense position;

flowing polishing fluid from the dispense arm in the first dispense position to a polishing surface to create a first fluid distribution;

polishing a substrate on the polishing surface having the first fluid distribution;

moving the dispense arm to a second dispense position;

flowing polishing fluid from the dispense arm in the second dispense position to the polishing surface to create a second fluid distribution; and

polishing the substrate on the polishing surface having the second fluid distribution.

11. The method of claim 10 further comprising:

rotating the dispense arm to a position clear of the polishing surface; and

increasing a flow of fluid from the dispense arm relative to the flows utilized to create the first and second fluid distributions.

12. The method of claim 10, wherein the step of moving further comprises:

changing an angular orientation of the dispense arm.

13. A method for processing a substrate, comprising:

flowing processing fluid to a surface through a fluid dispense arm;

processing a substrate on the surface in the presence of a first fluid distribution; and

moving the fluid dispense arm in-situ processing.

14. The method of claim 13, wherein the step of moving further comprises:

providing a second distribution of fluid on the surface; and

processing the substrate in the presence of the second distribution of fluid.

15. The method of claim 13 further comprising:

detecting a metric indicative of material removed while polishing the substrate in the presence of the first fluid distribution; and

moving the dispense arm in response to the detected metric.

16. The method of claim 13, wherein the step of moving the fluid dispense arm further comprises:

moving a fluid outlet disposed on the arm parallel to the polishing surface.

17. The method of claim 13, wherein the step of moving the fluid dispense arm further comprises:

rotating the arm.

18. The method of claim 13 further comprising:

moving the fluid dispense arm clear of the surface; and

flowing a fluid through the fluid dispense arm at an increased flow rate relative to a flow rate utilized to create the first fluid distribution.

19. The method of claim 18, wherein the flow rate in the position clear of the surface is greater than flow rates utilized to create the first polishing fluid distribution.

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